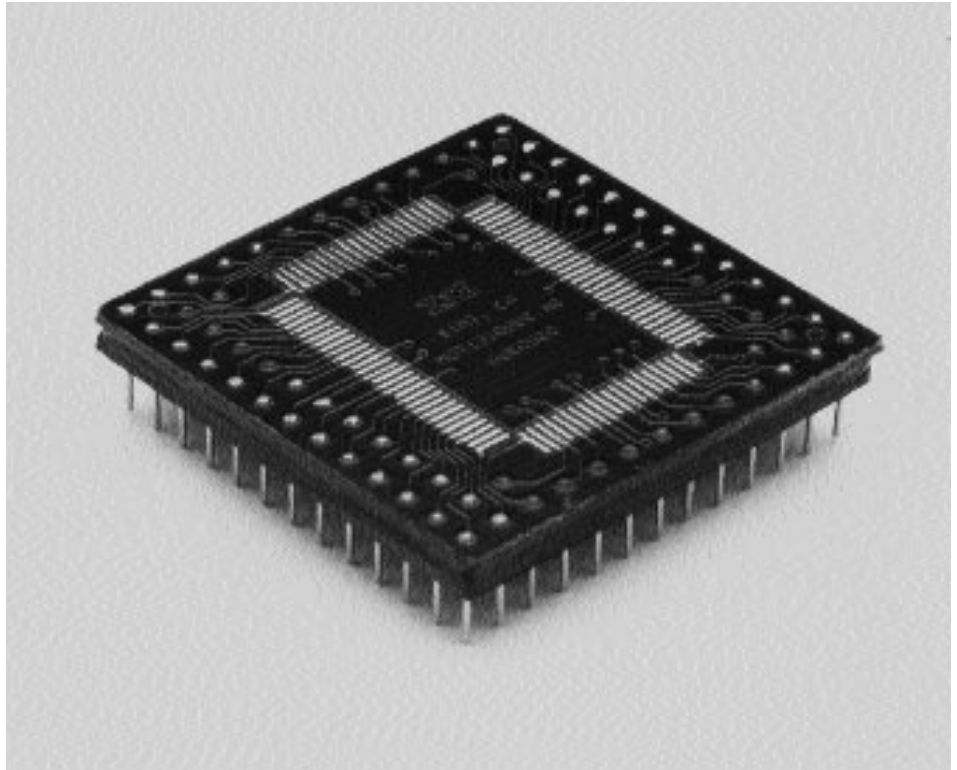


## PLCC or PQFP to PGA Adapter

- Installed Cost Savings Using Adapter Plus PQFP, Versus PGA
  - Makes Intel Chip Cost Effective For Thru-Hole Users
- Adapter Plus PQFP Form and Function Compatible With Intel PGA
  - Use Adapter Without Any Board Design Modifications
- Flexibility in Package Use
  - Allows Chip Users to Convert Between Different Package Styles Without Board Modification
- Capability of Adapters to Provide Custom Features to Specific Chip Users
  - Add Power/Ground Planes, De-Coupling Capacitors, Multiple Chips, etc. While Maintaining Package Footprint Compatibility



Interconnect Systems, Inc. has an adapter for converting a surface mount package to a through-hole (PGA) package. The i960<sup>®</sup> processor adapter allows the user to use the surface mount package without forcing direct fine-pitch surface mount on a large board assembly, and without any board re-design whatsoever. This is because ISI has developed an adapter design which allows existing package footprints to directly translate to each other.

PROCESSORS SUPPORTED:  
i960 Processor Family

CONTACT:  
Glen Griswold  
Interconnect Systems, Inc.  
2162 Union Place  
P.O. Box 1089  
Simi Valley, CA 93065  
Phone: (805) 581-5626  
FAX: (805) 581-5032

